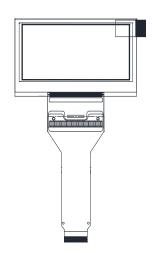


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COMPLIANT

### 128 x 64 Graphic OLED



#### **FEATURES**

• Type: graphic

Display format: 128 x 64 dotsBuilt-in controller: SSD1305

Duty cycle: 1/64+3 V power supply

• Interface: 6800, 8080, serial, and I<sup>2</sup>C

With polarizer

 Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

MECHANICAL DATA						
ITEM	ITEM STANDARD VALUE					
Module dimension	60.5 x 37.0 x 2.3					
Viewing area	56.35 x 28.05					
Active area	53.73 x 26.85	mm				
Dot size	0.39 x 0.39	mm				
Dot pitch	0.42 x 0.42					
Mounting hole	n/a					

ABSOLUTE MAXIMUM RATINGS								
ITEM	SYMBOL	STANDAF	RD VALUE					
I I EIVI	STINIBUL	MIN.	MAX.	UNIT				
Supply voltage for logic (1)(2)	$V_{DD}$	-0.3	4	V				
Supply voltage for display (1)(2)	V <sub>CC</sub>	0	15	V				
Operating temperature	T <sub>OP</sub>	-40	+80	°C				
Storage temperature	T <sub>STG</sub>	-40	+80	)				

#### **Notes**

- $^{(1)}$  All the above voltages are on the basis of "V<sub>SS</sub> = 0 V".
- (2) When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate

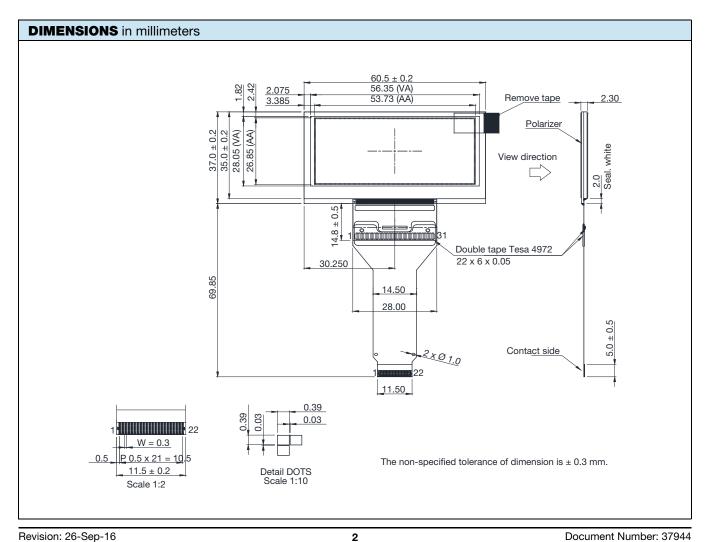
ELECTRICAL CHARACTERISTICS								
ITEM	SYMBOL	CONDITION	ST	ANDARD VA	LUE	UNIT		
I I EIVI	STMBOL CONDITION	MIN.	TYP.	MAX.	ONII			
Supply voltage for logic	$V_{DD}$	-	2.8	3.0	3.3			
Supply voltage for display	V <sub>CC</sub>	=	10	12	15			
Input high voltage	V <sub>IH</sub>	=	0.8 V <sub>DD</sub>	-	$V_{DD}$	V		
Input low voltage	V <sub>IL</sub>	-	0	-	0.2 V <sub>DD</sub>	V		
Output high voltage	V <sub>OH</sub>	=	0.9 V <sub>DD</sub>	-	$V_{DD}$			
Output low voltage	V <sub>OL</sub>	-	0	-	0.1 V <sub>DD</sub>			
50 % check board operating current	I <sub>CC</sub>	V <sub>CC</sub> = 12 V	22	23	25	mA		

OPTIONS	OPTIONS									
EMITTING COLOR					MOQ					
YELLOW	GREEN	RED	BLUE	WHITE	YELLOW	GREEN	RED	BLUE	WHITE	
Yes	-	1	ı	-	Yes	-	ı	-	ı	

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INTER	INTERFACE PIN FUNCTION							
PIN NO.	SYMBOL			F	UNCTION			
1	V <sub>CC</sub>	Power supply	for analog circuit	•				
2	V <sub>COMH</sub>	COM voltage	output. A capacit	or should be connec	ted between this pin a	ind V <sub>SS</sub> .		
3	I <sub>REF</sub>	Reference cu	rent input pin. A r	esistor should be co	nnected between this	pin and V <sub>SS</sub> .		
4 to 11	D7 to D0	Data bus.						
12	E/RD#	Data read ope	eration is initiated	when it is pull low.				
13	R / W#	Data write op	eration is initiated	when it is pull low.				
14	D / C#	Data / comma	and control. Pull h	igh for write / read di	splay data. Pull low fo	or write command	or read status.	
15	RES#	Reset signal i	nput. When it is lo	w, initialization of SS	D1305 is executed.			
16	CS#	Chip select in	put.					
17	D00	Communicati	ng protocol select	. These pins are MC	U interface selection in	nput. See the follo	owing table:	
17	BS2		I <sup>2</sup> C	68XX parallel	80XX parallel	Serial		
		BS1	1	0	1	0	7	
18	BS1	BS2	0	1	1	0	7	
							_	
19	$V_{DD}$	Power supply	for logic circuit.					
20	NC	No connectio	No connection.					
21	V <sub>SS</sub>	Ground.	Ground.					
22	V <sub>SS</sub>	Ground.						



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## 1. Module Classification Information

OLED 128 Y 064 F L P P 3 N 0 0 000

	Ø 0 6			
1	Brand: Vishay Int	tertechnology, Inc.		
2	Horizontal Format:	: 128 Columns		
3	Display Type: N→0	Character Type, H→Graphic Type, Y→Tab Type, O→Cog		
4	Vertical Format: 64	4 Lines		
5	Serials code			
		A : Amber R : RED		
6	Emitting Color	B: Blue W: White		
		G : Green L : Yellow		
7	Polarizer	P: With Polarizer; N: Without Polarizer		
8	Display Mode	P : Passive Matrix ; A: Active Matrix		
9	Driver Voltage	3: 3.0 V; 5: 5.0V		
10	Touch Panel	N: Without touch panel; T: With touch panel		
11	Products type	<ul><li>0 : Standard type</li><li>1. Sunlight Readable type</li><li>2. Transparent OLED (TOLED)</li><li>3. Flexible OLED</li><li>4. OLED for Lighting</li></ul>		
12	Product grades	Product grades:  0 : Standard(A-level)  2 : B-level  3 : C-level  4 : high class(AA-level)  5 : Customer offerings		
13	Serial No.	Application serial number(000~ZZZ)		



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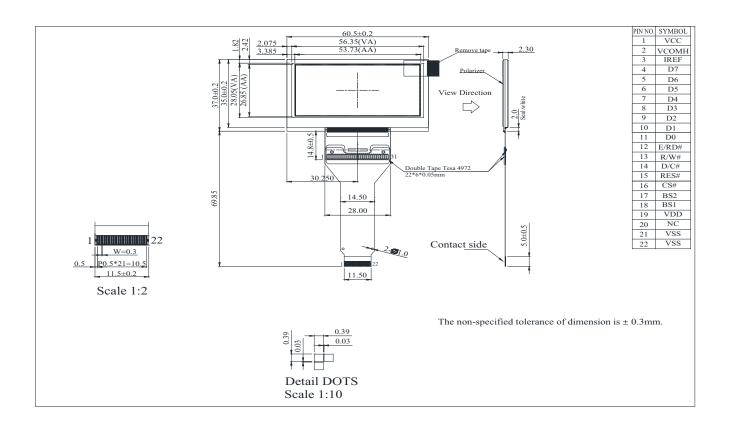
# **2.General Specification**

Item	Dimension	Unit			
Dot Matrix	128 x 64 Dots	_			
Module dimension	60.5 × 37.0 × 2.3	mm			
Active Area	53.73 × 26.85	mm			
Pixel Size	0.39 × 0.39	mm			
Pixel Pitch	0.42 × 0.42	mm			
Display Mode	Passive Matrix	l			
Display Color	Monochrome (Yellow)				
Drive Duty	1/64 Duty				



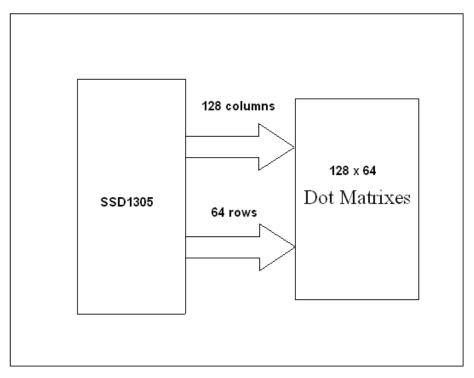
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## 3. Contour Drawing & Block Diagram



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#### **FUNCTION BLOCK DIAGRAM**



<sup>\*</sup>For more information, please refer to Application Note provided by Vishay



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# 4. Interface Pin Function

No.	Symbol	Function	Function				
1	VCC	Power suppl	Power supply for analog circuit.				
2	VCOMH		Output. A capac pin and VSS.	itor should be conn	ected		
3	IREF		urrent input pin. ould be connecte	d between this pin	and VSS.		
4~11	D7~D0	Data bus.					
12	E/RD#	Data read op	eration is initiate	d when it's pull low.			
13	R/W#	Data write or	eration is initiate	d when it's pull low.			
14	D/C#		and control. write/read display vrite command or				
15	RES#	Reset signal When it's lov		SSD1305 is execut	ed.		
16	CS#	Chip select in	nput.				
17	BS2			ct e selection input. Se	ee the		
		I20		80XX-parallel	Serial		
18	BS1	BS1 1	0	1	0		
		BS2 0	1	1	0		
19	VDD	Power suppl	Power supply for logic circuit.				
20	NC	No connection					
21	VSS	Ground.					
22	VSS	Ground.					



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# **5.Absolute Maximum Ratings**

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	4	V	1, 2
Supply Voltage for Display	VCC	0	15	V	1, 2
Operating Temperature	TOP	-40	+80	°C	-
Storage Temperature	TSTG	-40	+80	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 6 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



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# **6.Electrical Characteristics**

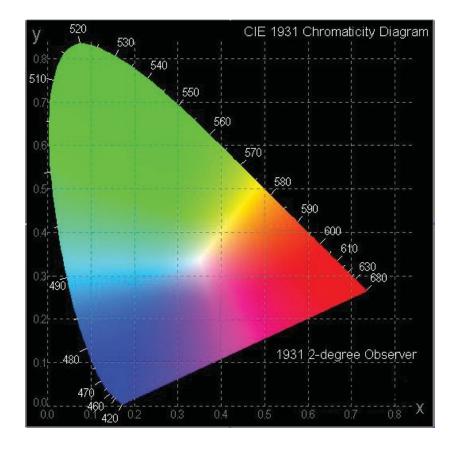
Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.8	3.0	3.3	V
Supply Voltage for Display	VCC	_	10	12	15	V
High Level Input	VIH	_	0.8×VDD	_	VDD	V
Low Level Input	VIL	_	0	_	0.2×VDD	V
High Level Output	VOH	_	0.9×VDD	_	VDD	V
Low Level Output	VOL	_	0	_	0.1×VDD	V
50% Check Board operatir Current	ng	VCC =12V	22	23	25	mA



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# 7. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ		160			deg
View / trigie	(Η)φ		160			deg
Contrast Ratio	CR	Dark	2000:1		_	_
Response Time	T rise	_		10		μs
Tresponse Time	T fall	_		10		μs
Display with 50% check	Board Brig	ghtness	60	80		cd/m2
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	





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## **8.OLED Lifetime**

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25°ℂ / Initial 50% check board brightness Typical Value	50,000 Hrs	_	Note

#### Notes:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



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# 9.Reliability

**Content of Reliability Test** 

Environmenta	I Test		T
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80 °C 240hrs	
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-40°C 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80 °C 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40 °C 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C,90% RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle.  -40 °C 25°C  30min 5min 30min 1 cycle	-40 °C/80 100 cycles	
Mechanical Te	st		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	
Others			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact) ±800v(air), RS=330 Ω CS=150pF 10 times	

<sup>\*\*\*</sup> Supply voltage for OLED system =Operating voltage at 25°C

### OLED-128Y064F-LPP3N00000



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#### Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5°C; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

#### **Evaluation criteria**

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within ± 50% of initial value.

#### APPENDIX:

#### **RESIDUE IMAGE**

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.

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# 10.Inspection specification

NO	Item	Criterion					AQL
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 OLED viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.		0.65			
02	Black or white spots on OLED (display only)	<ul><li>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.</li><li>2.2 Densely spaced: No more than two spots or lines within 3mm.</li></ul>			2.5		
03	OLED black spots, white spots, contamina tion (non-displ ay)	3.1 Round type: following drawing Φ=(x+y)/2	g		SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1	2.5
		3.2 Line type : (A	As followin Length $$ L $\leq$ 3.0 L $\leq$ 2.5 $$	Wid W ≦ 0.0 0.0		Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are vis judge using blac specifications, no to find, must che specify direction	k spot ot easy eck in	Φ ≦ 0.2 0.5 1.0	ze Φ ≦ 0.20 20 < Φ ≤ 0.50 60 < Φ ≤ 1.00 00 < Φ cal Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5



NO	Item	Criterion	AQL	
05	Scratches	Follow NO.3 OLED black spots, white spots, contamination		
	Gerarente	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length:  6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:		
	Chipped			
06	glass	area 1/2t < z ≤ 2t Not exceed 1/3k x ≤ 1/8a	2.5	
	9			
		Olf there are 2 or more chips, x is total length of each chip.  6.1.2 Corner crack: $ z$ : Chip thickness  y: Chip width  x: Chip length $z \le 1/2t$ Not over viewing $z \le 1/8a$ area $1/2t < z \le 2t$ Not exceed $1/3k$ $z \le 1/8a$		



Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:  y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t  6.2.2 Non-conductive portion:  y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t  y: Chip width x: Chip length z: Chip thickness y≤L x≤1/8a 0 < z≤t  OIf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.  OIf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack.  y: width x: length y≤1/3L x≤a	NO	Item	Criterion	AQL			
k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:  y: Chip width x: Chip length z: Chip thickness y≤0.5mm x≤1/8a 0 < z≤t  6.2.2 Non-conductive portion:  Glass crack  y: Chip width x: Chip length z: Chip thickness y≤ L x≤1/8a 0 < z≤t  Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.  Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack.  y: width x: length	110	110111		TIQL			
L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:    y: Chip width   x: Chip length   z: Chip thickness   y≤0.5mm   x≤1/8a   0 < z ≤ t     6.2.2 Non-conductive portion:    y: Chip width   x: Chip length   z: Chip thickness   z							
$\begin{array}{cccccccccccccccccccccccccccccccccccc$							
Glass crack  Glass crack  Glass crack  Glass crack  Glass crack  Glass crack  y: Chip width   x: Chip length   z: Chip thickness   y ≤ 0.5mm   x ≤ 1/8a   0 < z ≤ t   x ≤ 1/8a   x ≤ 1/8a							
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$							
$y \leq 0.5 \text{mm} \qquad x \leq 1/8 a \qquad 0 < z \leq t$ $6.2.2 \text{ Non-conductive portion:}$ $y : \text{Chip width} \qquad x : \text{Chip length} \qquad z : \text{Chip thickness}$ $y \leq L \qquad x \leq 1/8 a \qquad 0 < z \leq t$ $0 \text{ If the chipped area touches the ITO terminal, over } 2/3 \text{ of the ITO must remain and be inspected according to electrode terminal specifications.}$ $0 \text{ If the product will be heat sealed by the customer, the alignment mark not be damaged.}$ $6.2.3 \text{ Substrate protuberance and internal crack.}$ $y : \text{ width } \qquad x : \text{ length}$							
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Glass crack  y: Chip width  x: Chip length  z: Chip thickness  y≤ L  x≤1/8a  0 < z≤ t  Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.  Olf the product will be heat sealed by the customer, the alignment mark not be damaged.  6.2.3 Substrate protuberance and internal crack.  y: width  x: length			y: Chip width x: Chip length z: Chip thickness				
Glass crack    y							
y: Chip width x: Chip length z: Chip thickness y≤ L x≤1/8a 0 < z≤ t  Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.  If the product will be heat sealed by the customer, the alignment mark not be damaged.  6.2.3 Substrate protuberance and internal crack.  y: width x: length			6.2.2 Non-conductive portion:				
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			Υ .				
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y y y			$y \ge 1/3L$ $X \ge d$				
			у				





NO	Item	Criterion	AQL
07	Cracked glass	The OLED with extensive crack is not acceptable.	2.5
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using OLED spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	0.65 2.5 0.65
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65
10	PCB、COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, OLED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> </ul>	2.5 2.5 0.65 2.5 2.5 0.65 2.5
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65





NO	Item	Criterion	AQL
12	General appearance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 OLED pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> <li>12.11 Product dimension and structure must conform to product specification sheet.</li> </ul>	AQL  2.5  0.65  2.5  2.5  2.5  2.5  0.65  0.65  0.65  0.65

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	A Normal B Dark Pixel C Light Pixel

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## 11.Precautions in use of OLED Modules

### **Modules**

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3)Don't disassemble the OLED display module.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist OLED display module.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8)It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9)Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time...
- (10) Vishay has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Vishay have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Vishay have the right to modify the version.)

#### 11.1. Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
  - \* Scotch Mending Tape No. 810 or an equivalent
  - Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent

such as ethyl alcohol, since the surface of the polarizer will become cloudy.

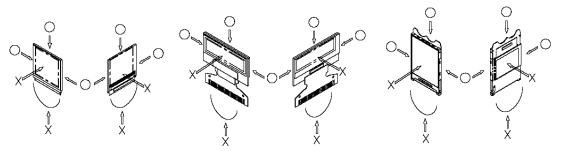
Also, pay attention that the following liquid and solvent may spoil the polarizer:

- \* Water
- \* Ketone
- \* Aromatic Solvents
- (6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts.

These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



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- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- \* Be sure to make human body grounding when handling OLED display modules.
- \* Be sure to ground tools to use or assembly such as soldering irons.
- \* To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- \* Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

#### 11.2. Storage Precautions

(1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. and, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.

(We recommend you to store these modules in the packaged state when they were shipped from Vishay.

At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.

(2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

#### 11.3. Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
- (4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
- (5) As for EMI, take necessary measures on the equipment side basically.

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- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module.
- \* Connection (contact) to any other potential than the above may lead to rupture of the IC.

#### 11.4. Precautions when disposing of the OLED display modules

1) Request the qualified companies to handle industrial wastes when disposing of the OLED display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

### 11.5. Other Precautions

- (1) When an OLED display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur.
- Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module.
- (2) To protect OLED display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OLED display modules.
- \* Pins and electrodes
- \* Pattern layouts such as the TCP & FPC
- (3) With this OLED display module, the OLED driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OLED driver is exposed to light, malfunctioning may occur.
- \* Design the product and installation method so that the OLED driver may be shielded from light in actual usage.
- \* Design the product and installation method so that the OLED driver may be shielded from light during the inspection processes.
- (4) Although this OLED display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.
- (5) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.
- (6)Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.
- (7)Our company will has the right to upgrade and modify the product function.

### **Legal Disclaimer Notice**



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